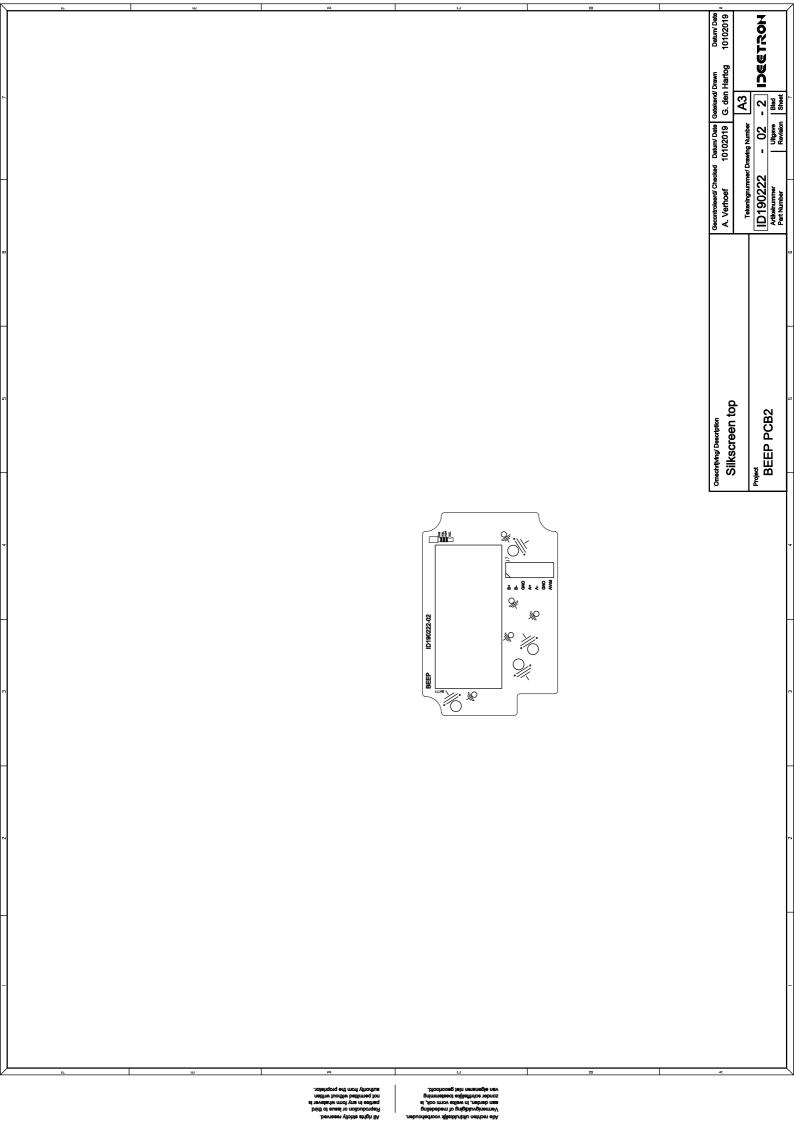
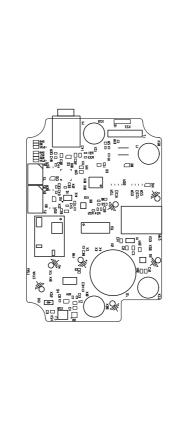
BLAD	OMSCHRIJVING	FORMAAT
SHEET	DESCRIPTION	FORMAT
_	PAGE INDEX	A3
2	SILKSCREEN TOP	A3
3	SILKSCREEN BOTTOM	A3
4	COPPER TOP	A3
5	COPPER BOTTOM	A3
9	INNER LAYER 1	A3
7	INNER LAYER 2	A3
8	ANTI SOLDER MASK TOP	A3
6	ANTI SOLDER MASK BOTTOM	A3
10	PASTEMASK BOTTOM	A3
11	MECHENICAL & DRILL DRAWING	A3
12	PCB SPECIFICATIONS	

Omschrijving/ Description	Gecontroleerd/ Checked Datum/ Date Getekend/ Drawn	m/ Date	Getekend/		Datum/ Date
Page index PCB documentation	A. Verhoef 10102019 G. den Hartog 10102019	2019	G. den	Hartog	10102019
	Tekeningnummer/ Drawing Tekeningnummer/	Number	A3		
	Burney (Service)				
	ID190222 - 02 - 1 ID€€TAON	02	- 1	DAG.	XOY!
	Artikelnummer	Uitgave Blad	Blad		





Omechtipling/ Description

Silkscreen bottom

Project

Project

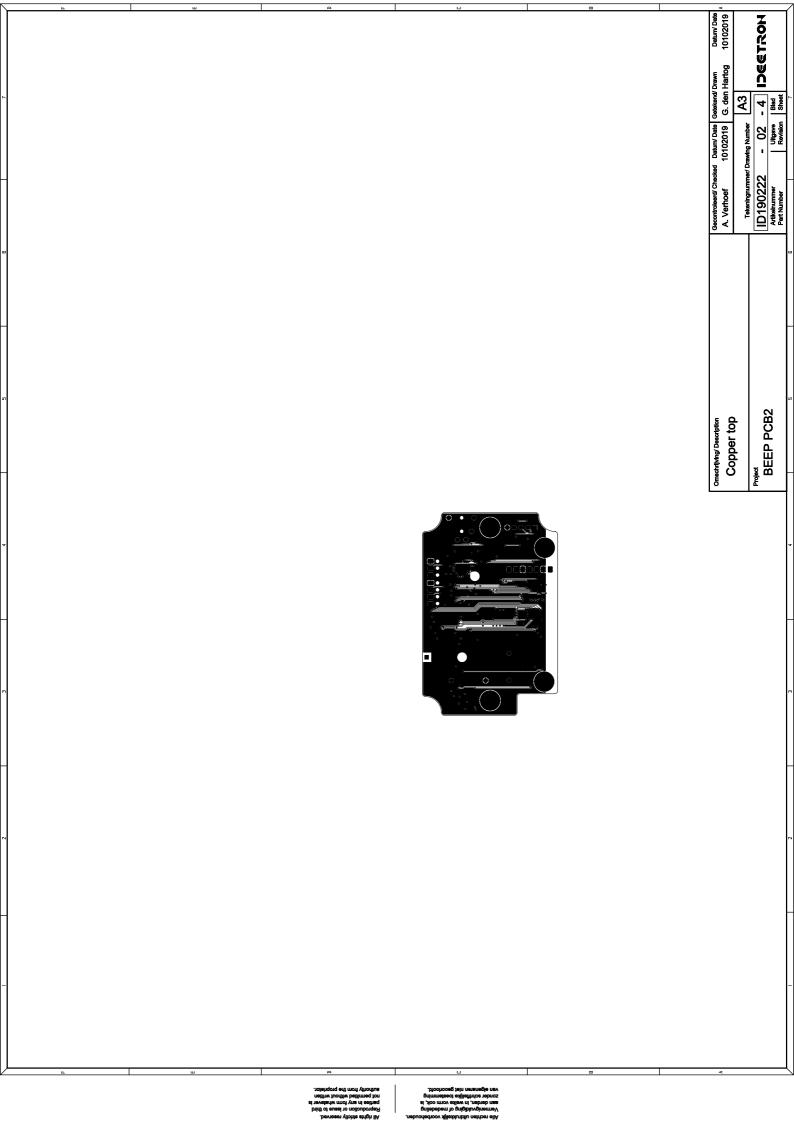
BEEP PCB2

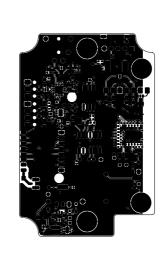
BEEP PCB2

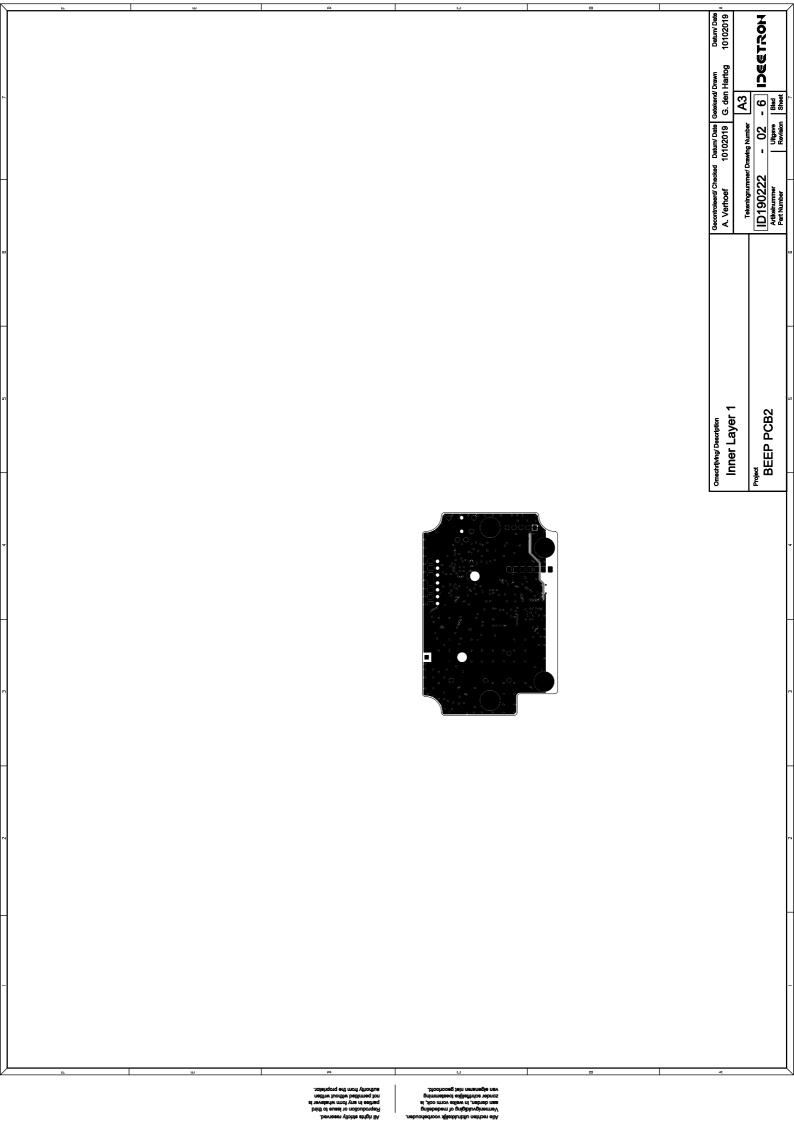
ID190222 - 02 - 3

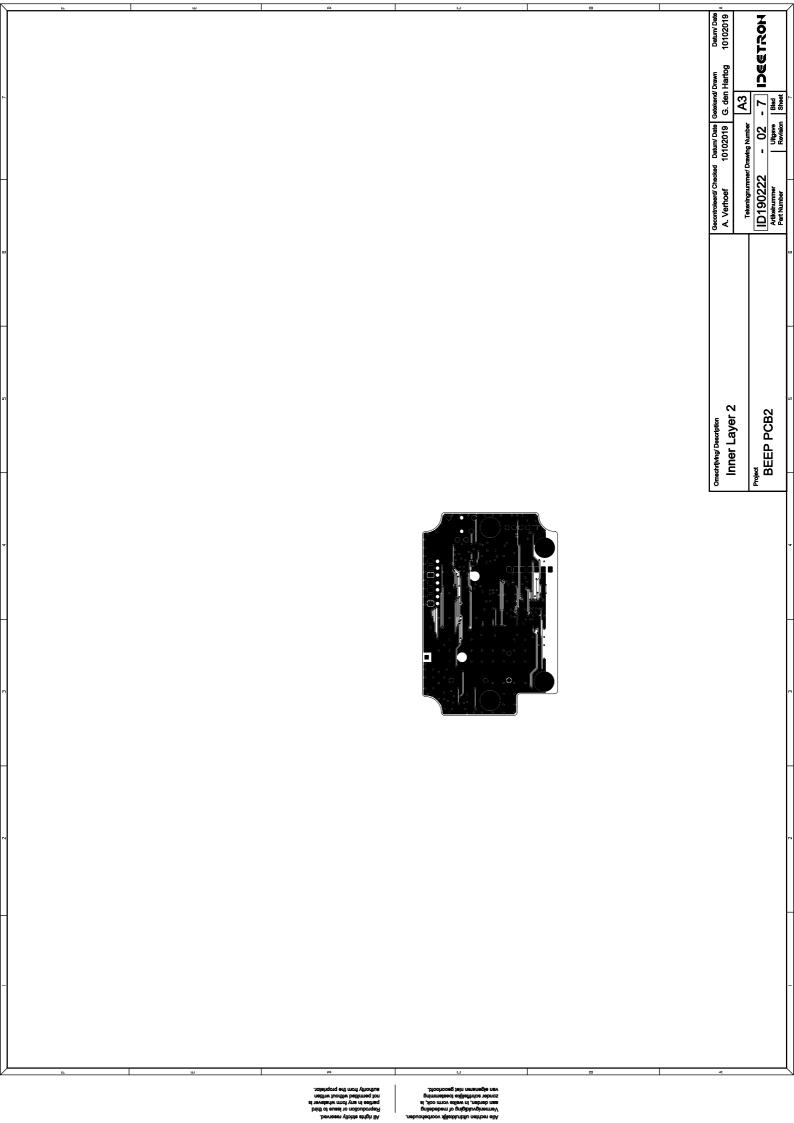
Addisolvummer Parking Number

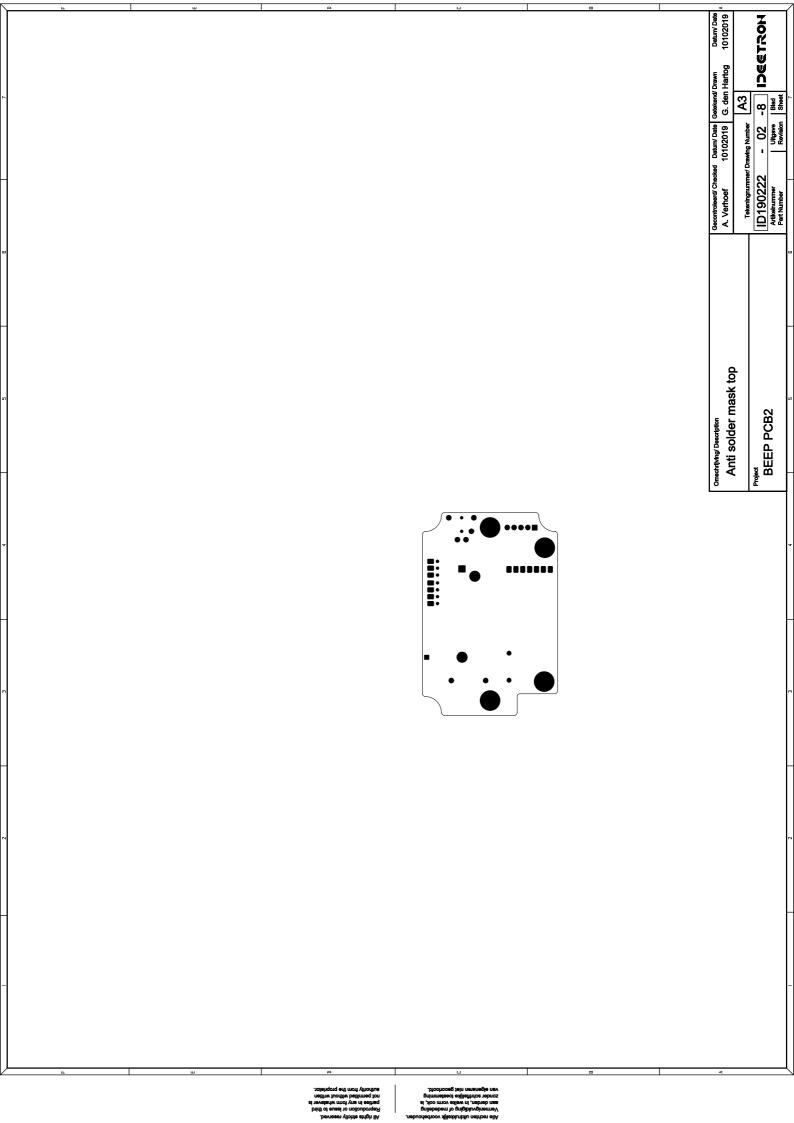
Revision Sheet

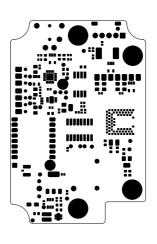






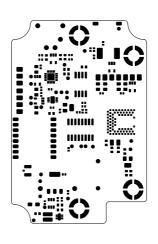






| Tekenthgnummer/ Drawing Number | A3 | | ID490222 - 02 -9 | Addientummer | Uitgave | Blad | Sheet | Revision | Sheet Gecontroleerd/ Checked Datum/ Date Getekend/ Drawn
A. Verhoef 10102019 G. den Hartog Anti solder mask bottom Project
BEEP PCB2 Omschrijving/ Description

Datum/ Date 10102019



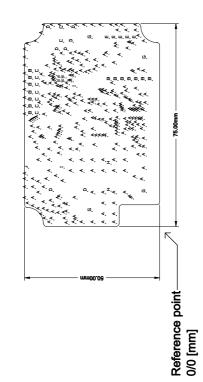
Omednityking Description
Paste mask bottom
Paste mask bottom
Paste mask bottom
A. Verthoef 10102019 G. den Hartog 10102019
Project
Project
BEEP PCB2
Part Number Revision Sheet

	Count	341	7	1	7	9	6	4	14	7	4
	Letter	٧	Ŧ	ſ	I	Ξ	၁	Q	8	-	ŋ
DIII I abie	Plate Through	YES	YES	XES	YES	YES	ON	YES	YES	ON	ON
	Length	0000	0000	0.000	0000	000'0	000'0	000'0	000'0	000'0	0.000
	Size	0.200	0.300	0.7112	0.800	1.000	1.09982	1.100	1.1938	3.400	4.400

The hole diameters for plated holes are after plating

Tolerances:

Plated holes -0.1 / +0.1mm Non-plated holes -0.05 / +0.05mm



Gecontroleerd/ Checked Datum/ Date Getekend/ Drawn
A. Verhoef 10102019 G. den Hartog ID190222 Artikelnummer Part Number Mechanical & Drill drawing Project
BEEP PCB2

Omschrijving/ Description

Datum/ Date 10102019

SPECIFICATIONS PRINTED CIRCUIT BOARD

LAYER STACK

NUMBER OF LAYERS	4	Corresponding Gerberfiles		Layer name/ material	
COPPER THICKNESS	All electrical layers: 35µm	<filename>_LAYOUT_TOP.gbr</filename>			
FINISHED BOARD	1,6 mm +/- 10% after standard finishing/plating	<filename>_SOLDERMASK_TOP.gbr</filename>			
THICKNESS	(measured without selective plating)	<filename>_TOP.gbr_</filename>		Toplayer	
HOLES	Drilled and plated (non-plated, see tabel)	<filename>_INNER1.gbr _</filename>		Prepreg Inner Layer 1	
FINISH	Leadfree finish	<filename>_INNER2.gbr _</filename>			Assy
SOLDERMASK	Green epoxy soldermask Top/Bottom Wet film - Thickness min 20µm	_ rfllename>_BOT.gbr		Bottomlayer	
SELECTIVE PLATING	попе	<pre><ili><pre></pre></ili></pre>			
BASE MATERIAL	18400				
APPLICABLE STANDARDS		Drillfles:	Assv 1 (plated):	<fi><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><pre></pre><</fi>	م
1. IPC-A-600G - "Acceptibility for	1. IPC-A-600G - "Acceptibility for Printed Circuit Boards" - September 2004		Assy 1 (non-plated):	<filename>_DNP.gbr</filename>	.gpr
2. IPC-6011 - "Generic Specifical	2. IPC-6011 - "Generic Specification for Printed Boards" - July 1996	File for selective plating (if applicable):	applicable):	<filename>_SELPL.gbr</filename>	7.gbr

IDEETRON

4. IPC-4101B, incl. Amendment 1 & 2 - "Specifications for Base Materials for Rigid and Multilayer Printed Boards" - May 2007

3. IPC-6012B, Class 3 - "Qualification and Performance for Rigid Printed Boards" - January 2007

<filename> = ID190222-02_xx DATECODE xx_

Omednitying Description
PCB specifications
Project
Project
ID190222 - 02 -12
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